# Two part thermal gel pad / XK-S10

## Features:

1:1 mix
(no cure by-product)
Low stress applications
Easy to use
Fast cure by heating

## Applications

Automotive electronics
Telecommunications
Computer&peripherals
Thermally conductive & vibration dampening
Between any heat-generating semiconductor and a heat sink

| | XK-S10 | METHOD | UNIT |
|---|---|---|---|
| Color / Part A | White | Visual | |
| Color / Part B | Yellow | Visual | |
| Features | Soft gel | - | - |
| Density | 1.8 | ASTM D792 | g/cm3 |
| Before Cured Property | | | |
| A:B | 1:1 | - | - |
| Viscosity@25℃ | 230 | ASTM D2196 | Pa.s |
| Shelf Life @ 25℃ | 6 | | month |
| After Cured Property | | | |
| Color | Yellow | Visual | - |
| Cure Schedule 1 | 6 hrs/25℃ | | |
| Cure Schedule 2 | 40 min/80℃ | | |
| Cure Schedule 3 | 10 min/100℃ | | |
| Working time | 120 min/25℃ | | |
| Hardness | 60 | ASTM D2240 | Shore 00 |
| | 30 | JIS K7312 | AskerC |
| Tensile Strength. | 0.4 | ASTM D412 | Mpa |
| Elongation | >50 | ASTM D412 | % |
| Continuous Use Temp | -40~150 | | ℃ |
| Electrical Property | | | |
| Dielectric strength | >10 | ASTM D149 | KV/mm |
| Volume resistivity | $>10^{12}$ | ASTM D257 | Ohm-cm |
| Dielectric Constant | 5 | ASTM D150 | (1KHz) |
| Flame Rating | V-0 | UL94 | |
| Thermal Property | | | |
| Thermal Conductivity | 1.0 | ASTM D5470 | W/m*K |
| Heat Capacity | 1 | ASTM E1269 | J/g-K |

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# 使用操作程序:

1. AB 比例 1:1 ， AB 胶两剂要混合均匀
2. 使用工具: 自动点胶机 或 手动供料枪
3. 熟化时间与点胶量(成品厚度) 有关

| Curing temperature ℃ | Curing time |
|---|---|
| 25 | 20 hr |
| 50 | 120~300min |
| 80 | 20~100min |
| 100 | 10~20min |
| 150 | 1~3 min |

## 注意要点

接触面:
如果与含硫磺,磷,氮气化物,氮及含有机金属塩等物质接触时,阻害其表面硬化,轻微者阻害其表面与接触面的硬化,严重者造成永久,完全性不硬化.

环境面:
除要求混合比例之正确外,在混胶使用之容器(如:纸杯,塑料杯…),因为容器内壁之油腊,塑料中可塑剂的渗透关系,烤箱内部因为烘烤过环氧树脂,凡立水..等,会造成污染

因此在使用之前,清扫并干燥机器,特别是与上述物质有接触可能,请先行做试验

## 保存方法

1. 保存方式,在未混合使用前,室温 25 度 C 以下可保存 12 个月
2. AB 剂混合后需一次用完,无法留至日后继续使用